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**W25Q16JV**



***spi*flash<sup>®</sup>**

**3V 16M-BIT  
SERIAL FLASH MEMORY WITH  
DUAL/QUAD SPI**



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## 1. GENERAL DESCRIPTIONS

The W25Q16JV (16M-bit) Serial Flash memory provides a storage solution for systems with limited space, pins and power. The 25Q series offers flexibility and performance well beyond ordinary Serial Flash devices. They are ideal for code shadowing to RAM, executing code directly from Dual/Quad SPI (XIP) and storing voice, text and data. The device operates on a single 2.7V to 3.6V power supply with current consumption as low as 1 $\mu$ A for power-down.

The W25Q16JV array is organized into 8,192 programmable pages of 256-bytes each. Up to 256 bytes can be programmed at a time. Pages can be erased in groups of 16 (4KB sector erase), groups of 128 (32KB block erase), groups of 256 (64KB block erase) or the entire chip (chip erase). The W25Q16JV has 512 erasable sectors and 32 erasable blocks respectively. The small 4KB sectors allow for greater flexibility in applications that require data and parameter storage. (See figure 2.)

The W25Q16JV supports the standard Serial Peripheral Interface (SPI), and a high performance Dual/Quad output as well as Dual/Quad I/O SPI: Serial Clock, Chip Select, Serial Data I/O0 (DI), I/O1 (DO), I/O2, and I/O3. SPI clock frequencies of up to 133MHz are supported allowing equivalent clock rates of 266MHz (133MHz x 2) for Dual I/O and 532MHz (133MHz x 4) for Quad I/O when using the Fast Read Dual/Quad I/O instructions. These transfer rates can outperform standard Asynchronous 8 and 16-bit Parallel Flash memories.

Additionally, the device supports JEDEC standard manufacturer and device ID and SFDP Register, a 64-bit Unique Serial Number and three 256-bytes Security Registers.

## 2. FEATURES

- **New Family of SpiFlash Memories**
  - W25Q16JV: 16M-bit / 2M-byte (2,097,152)
  - Standard SPI: CLK, /CS, DI, DO
  - Dual SPI: CLK, /CS, IO<sub>0</sub>, IO<sub>1</sub>
  - Quad SPI: CLK, /CS, IO<sub>0</sub>, IO<sub>1</sub>, IO<sub>2</sub>, IO<sub>3</sub>
  - Software & Hardware Reset<sup>(1)</sup>
- **Highest Performance Serial Flash**
  - 133MHz Single, Dual/Quad SPI clocks
  - 266/532MHz equivalent Dual/Quad SPI
  - 66MB/S continuous data transfer rate
  - Min. 100K Program-Erase cycles per sector
  - More than 20-year data retention
- **Efficient “Continuous Read”**
  - Continuous Read with 8/16/32/64-Byte Wrap
  - As few as 8 clocks to address memory
  - Allows true XIP (execute in place) operation
  - Outperforms X16 Parallel Flash
- **Low Power, Wide Temperature Range**
  - Single 2.7V to 3.6V supply
  - -40°C to +85°C operating range
  - -40°C to +105°C operating range
  - <1 $\mu$ A Power-down (typ.)
- **Flexible Architecture with 4KB sectors**
  - Uniform Sector/Block Erase (4K/32K/64K-Byte)
  - Program 1 to 256 byte per programmable page
  - Erase/Program Suspend & Resume
- **Advanced Security Features**
  - Software and Hardware Write-Protect
  - Power Supply Lock-Down and
  - Special OTP protection<sup>(2)</sup>
  - Top/Bottom, Complement array protection
  - Individual Block/Sector array protection
  - 64-Bit Unique ID for each device
  - Discoverable Parameters (SFDP) Register
  - 3X256-Bytes Security Registers with OTP locks
  - Volatile & Non-volatile Status Register Bits
- **Space Efficient Packaging**
  - 8-pin SOIC 150-mil / 208-mil
  - 8-pad USON 2X3mm/4x3-mm
  - 8-pad XSON 4x4-mm
  - 8-pad WSON 6x5-mm
  - 8-ball WLCSP
  - Contact Winbond for KGD and other options

Note: 1. Hardware /RESET pin is only available on SOIC-16 & TFBGA packages

2. Please contact Winbond for details.



### 3. PACKAGE TYPES AND PIN CONFIGURATIONS

#### 3.1 Pin Configuration SOIC 150/208-mil

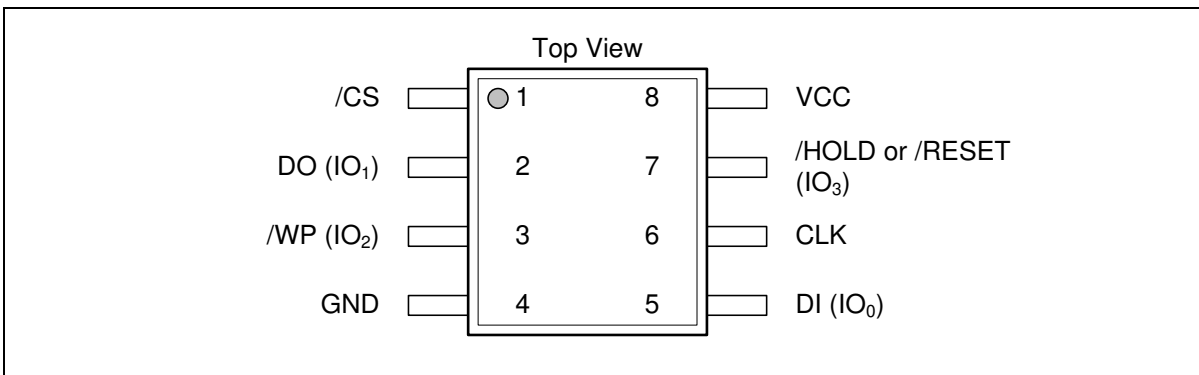


Figure 1a. Pin Assignments, 8-pin SOIC150-mil/208-mil (Package Code SN, SS)

#### 3.2 Pad Configuration WSON 6x5-mm & USON 2x3-mm/4x3-mm, XSON 4x4-mm

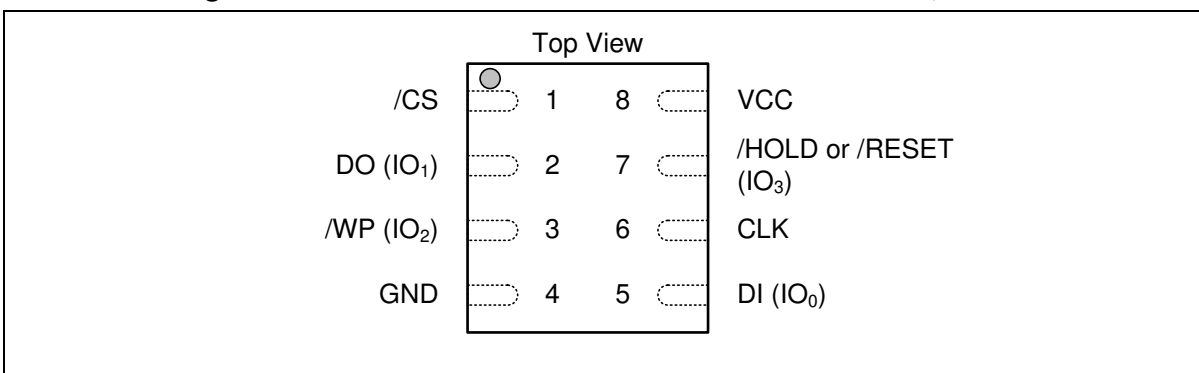


Figure 1b. Pad Assignments, 8-pad WSON 6x5-mm, USON 2x3-mm/4x3-mm, XSON 4x4-mm (Package Code ZP, UX, UU, XG)

#### 3.3 Pin Description SOIC 150/208-mil, WSON 6x5-mm, USON 2x3-mm/4x3-mm, XSON 4x4-mm

PIN NO.	PIN NAME	I/O	FUNCTION
1	/CS	I	Chip Select Input
2	DO (IO1)	I/O	Data Output (Data Input Output 1) <sup>(1)</sup>
3	/WP (IO2)	I/O	Write Protect Input (Data Input Output 2) <sup>(2)</sup>
4	GND		Ground
5	DI (IO0)	I/O	Data Input (Data Input Output 0) <sup>(1)</sup>
6	CLK	I	Serial Clock Input
7	/HOLD or /RESET (IO3)	I/O	Hold or Reset Input (Data Input Output 3) <sup>(2)</sup>
8	VCC		Power Supply

#### Notes:

- IO0 and IO1 are used for Standard and Dual SPI instructions
- IO0 – IO3 are used for Quad SPI instructions, /HOLD (or /RESET) function is only available for Standard/Dual SPI.



### 3.4 Ball Configuration WLCSP

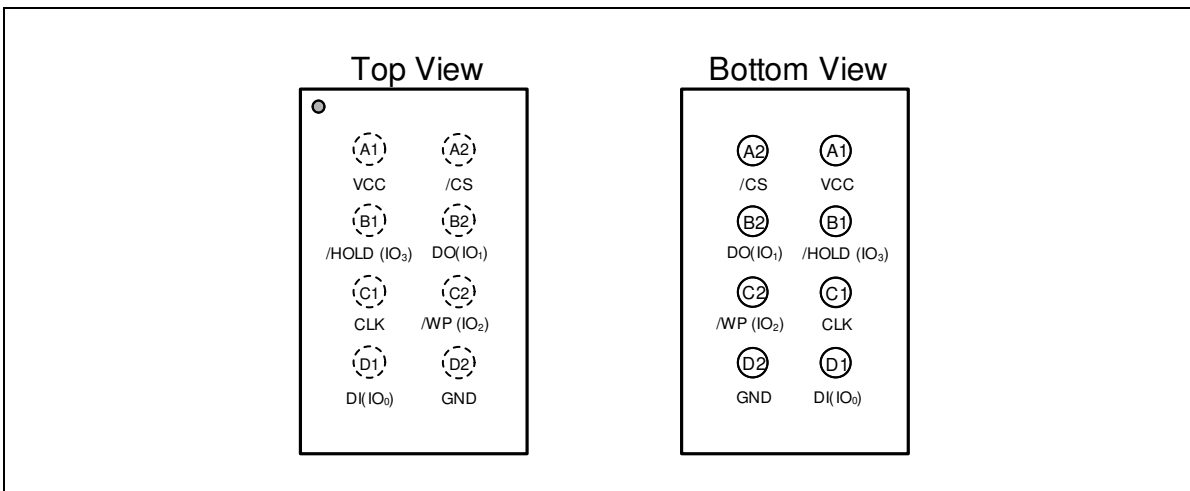


Figure 1c. W25Q16JV Ball Assignments, 8-ball WLCSP (Package Code BY)

### 3.5 Ball Description WLCSP

BALL NO.	PIN NAME	I/O	FUNCTION
A1	VCC		Power Supply
A2	/CS	I	Chip Select Input
B1	/HOLD or /RESET (IO3)	I/O	Hold or Reset Input (Data Input Output 3) <sup>(2)</sup>
B2	DO (IO1)	I/O	Data Output (Data Input Output 1) <sup>*1</sup>
C1	CLK	I	Serial Clock Input
C2	/WP (IO2)	I/O	Write Protect Input (Data Input Output 2) <sup>(2)</sup>
D1	DI (IO0)	I/O	Data Input (Data Input Output 0) <sup>*1</sup>
D2	GND		Ground

**Notes:**

- IO0 and IO1 are used for Standard and Dual SPI instructions
- IO0 – IO3 are used for Quad SPI instructions, /HOLD (or /RESET) functions are only available for Standard/Dual SPI.





## 4. PIN DESCRIPTIONS

### 4.1 Chip Select (/CS)

The SPI Chip Select (/CS) pin enables and disables device operation. When /CS is high the device is deselected and the Serial Data Output (DO, or IO0, IO1, IO2, IO3) pins are at high impedance. When deselected, the device's power consumption will be at standby levels unless an internal erase, program or write status register cycle is in progress. When /CS is brought low the device will be selected, power consumption will increase to active levels and instructions can be written to and data read from the device. After power-up, /CS must transition from high to low before a new instruction will be accepted. The /CS input must track the VCC supply level at power-up and power-down (see "Write Protection" and Figure 58). If needed a pull-up resistor on the /CS pin can be used to accomplish this.

### 4.2 Serial Data Input, Output and IOs (DI, DO and IO0, IO1, IO2, IO3)

The W25Q16JV supports standard SPI, Dual SPI and Quad SPI operation. Standard SPI instructions use the unidirectional DI (input) pin to serially write instructions, addresses or data to the device on the rising edge of the Serial Clock (CLK) input pin. Standard SPI also uses the unidirectional DO (output) to read data or status from the device on the falling edge of CLK.

Dual and Quad SPI instructions use the bidirectional IO pins to serially write instructions, addresses or data to the device on the rising edge of CLK and read data or status from the device on the falling edge of CLK. Quad SPI instructions require the non-volatile Quad Enable bit (QE) in Status Register-2 to be set. When QE=1, the /WP pin becomes IO2 and the /HOLD pin becomes IO3.

### 4.3 Write Protect (/WP)

The Write Protect (/WP) pin can be used to prevent the Status Register from being written. Used in conjunction with the Status Register's Block Protect (CMP, SEC, TB, BP2, BP1 and BP0) bits and Status Register Protect (SRP) bits, a portion as small as a 4KB sector or the entire memory array can be hardware protected. The /WP pin is active low.

### 4.4 HOLD (/HOLD)

The /HOLD pin allows the device to be paused while it is actively selected. When /HOLD is brought low, while /CS is low, the DO pin will be at high impedance and signals on the DI and CLK pins will be ignored (don't care). When /HOLD is brought high, device operation can resume. The /HOLD function can be useful when multiple devices are sharing the same SPI signals. The /HOLD pin is active low. When the QE bit of Status Register-2 is set for Quad I/O, the /HOLD pin function is not available since this pin is used for IO3. See Figure 1a-c for the pin configuration of Quad I/O operation.

### 4.5 Serial Clock (CLK)

The SPI Serial Clock Input (CLK) pin provides the timing for serial input and output operations. ("See SPI Operations")

### 4.1 Reset (/RESET)<sup>(1)</sup>

A dedicated hardware /RESET pin is available on SOIC-16 and TFBGA packages. When it's driven low for a minimum period of ~1 $\mu$ S, this device will terminate any external or internal operations and return to its power-on state.

#### Note:

1. Hardware /RESET pin is available on SOIC-16 or TFBGA; please contact Winbond for this package.



5. BLOCK DIAGRAM

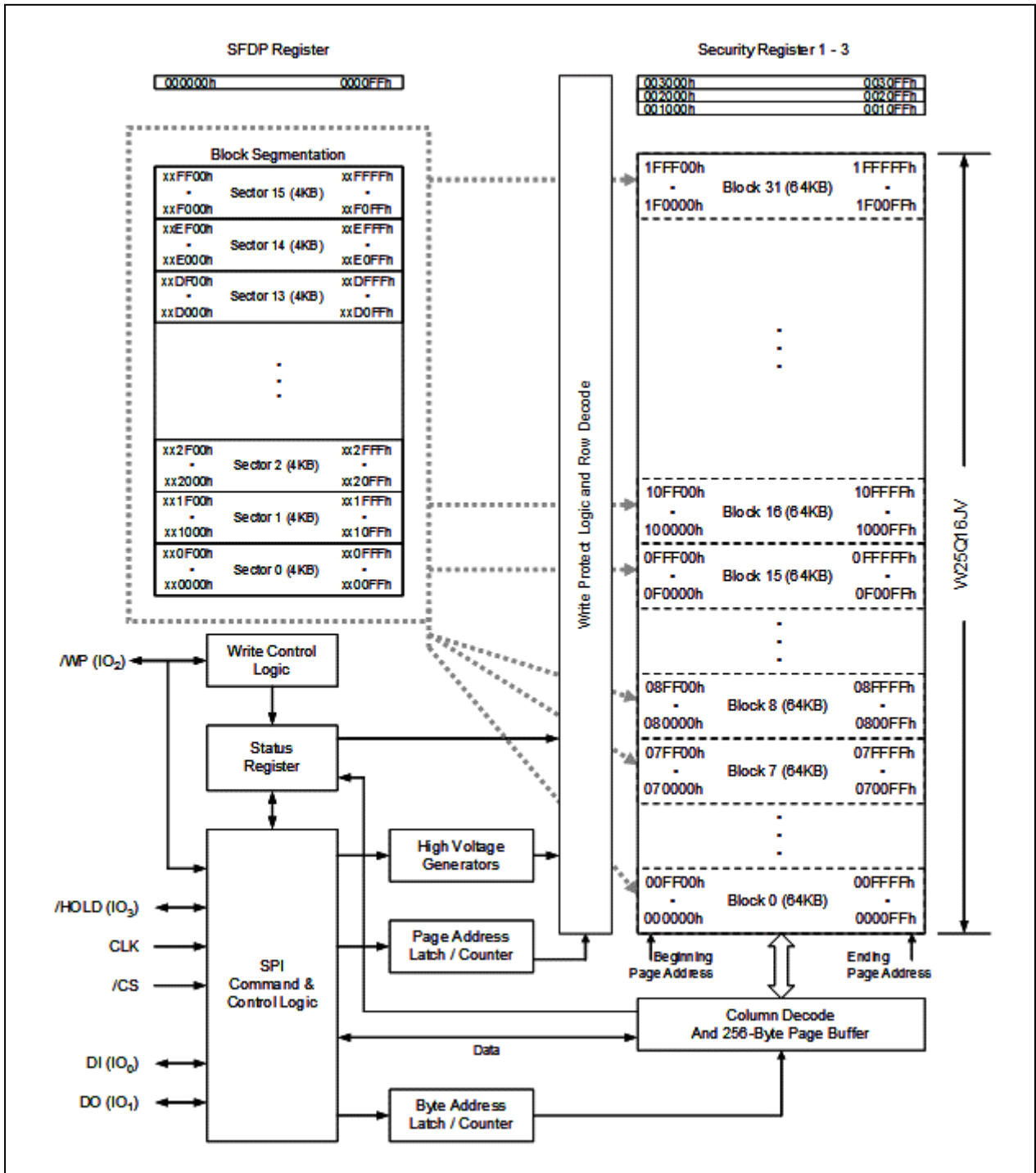


Figure 2. W25Q16JV Serial Flash Memory Block Diagram



## 6. FUNCTIONAL DESCRIPTIONS

### 6.1 Standard SPI Instructions

The W25Q16JV is accessed through an SPI compatible bus consisting of four signals: Serial Clock (CLK), Chip Select (/CS), Serial Data Input (DI) and Serial Data Output (DO). Standard SPI instructions use the DI input pin to serially write instructions, addresses or data to the device on the rising edge of CLK. The DO output pin is used to read data or status from the device on the falling edge of CLK.

SPI bus operation Mode 0 (0,0) and 3 (1,1) are supported. The primary difference between Mode 0 and Mode 3 concerns the normal state of the CLK signal when the SPI bus master is in standby and data is not being transferred to the Serial Flash. For Mode 0, the CLK signal is normally low on the falling and rising edges of /CS. For Mode 3, the CLK signal is normally high on the falling and rising edges of /CS.

### 6.2 Dual SPI Instructions

The W25Q16JV supports Dual SPI operation when using instructions such as “Fast Read Dual Output (3Bh)” and “Fast Read Dual I/O (BBh)”. These instructions allow data to be transferred to or from the device at two to three times the rate of ordinary Serial Flash devices. The Dual SPI Read instructions are ideal for quickly downloading code to RAM upon power-up (code-shadowing) or for executing non-speed-critical code directly from the SPI bus (XIP). When using Dual SPI instructions, the DI and DO pins become bidirectional I/O pins: IO0 and IO1.

### 6.1 Quad SPI Instructions

The W25Q16JV supports Quad SPI operation when using instructions such as “Fast Read Quad Output (6Bh)”, and “Fast Read Quad I/O (EBh)”. These instructions allow data to be transferred to or from the device four to six times the rate of ordinary Serial Flash. When using Quad SPI instructions, the DI and DO pins become bidirectional IO0 and IO1, with the additional I/O pins: IO2, IO3.

### 6.2 Software Reset & Hardware /RESET pin

The W25Q16JV can be reset to the initial power-on state by a software Reset sequence. This sequence must include two consecutive instructions: Enable Reset (66h) & Reset (99h). If the instruction sequence is successfully accepted, the device will take approximately 30 $\mu$ S ( $t_{RST}$ ) to reset. No instruction will be accepted during the reset period. For the SOIC-16 and TFBGA packages, W25Q16JV provides a dedicated hardware /RESET pin. Drive the /RESET pin low for a minimum period of  $\sim$ 1 $\mu$ S ( $t_{RESET^*}$ ) will interrupt any on-going external/internal operations and reset the device to its initial power-on state. Hardware /RESET pin has higher priority than other SPI input signals (/CS, CLK, IOs).

#### Note:

1. Hardware /RESET pin is available on SOIC-16 or TFBGA; please contact Winbond for his package.
2. While a faster /RESET pulse (as short as a few hundred nanoseconds) will often reset the device, a 1us minimum is recommended to ensure reliable operation.
3. There is an internal pull-up resistor for the dedicated /RESET pin on the SOIC-16 package. If the reset function is not needed, this pin can be left floating in the system.



### 6.3 Write Protection

Applications that use non-volatile memory must take into consideration the possibility of noise and other adverse system conditions that may compromise data integrity. To address this concern, the W25Q16JV provides several means to protect the data from inadvertent writes.

### 6.4 Write Protect Features

- Device resets when VCC is below threshold
- Time delay write disable after Power-up
- Write enable/disable instructions and automatic write disable after erase or program
- Software and Hardware (/WP pin) write protection using Status Registers
- Additional Individual Block/Sector Locks for array protection
- Write Protection using Power-down instruction
- Lock Down write protection for Status Register until the next power-up
- One Time Program (OTP) write protection for array and Security Registers using Status Register\*

\* Note: This feature is available upon special order. Please contact Winbond for details.

Upon power-up or at power-down, the W25Q16JV will maintain a reset condition while VCC is below the threshold value of VWI, (See Power-up Timing and Voltage Levels and Figure 43). While reset, all operations are disabled and no instructions are recognized. During power-up and after the VCC voltage exceeds VWI, all program and erase related instructions are further disabled for a time delay of tPUW. This includes the Write Enable, Page Program, Sector Erase, Block Erase, Chip Erase and the Write Status Register instructions. Note that the chip select pin (/CS) must track the VCC supply level at power-up until the VCC-min level and tvSL time delay is reached, and it must also track the VCC supply level at power-down to prevent adverse command sequence. If needed a pull-up resistor on /CS can be used to accomplish this.

After power-up the device is automatically placed in a write-disabled state with the Status Register Write Enable Latch (WEL) set to a 0. A Write Enable instruction must be issued before a Page Program, Sector Erase, Block Erase, Chip Erase or Write Status Register instruction will be accepted. After completing a program, erase or write instruction the Write Enable Latch (WEL) is automatically cleared to a write-disabled state of 0.

Software controlled write protection is facilitated using the Write Status Register instruction and setting the Status Register Protect (SRP, SRL) and Block Protect (CMP, TB, BP[2:0]) bits. These settings allow a portion or the entire memory array to be configured as read only. Used in conjunction with the Write Protect (/WP) pin, changes to the Status Register can be enabled or disabled under hardware control. See Status Register section for further information. Additionally, the Power-down instruction offers an extra level of write protection as all instructions are ignored except for the Release Power-down instruction.

The W25Q16JV also provides another Write Protect method using the Individual Block Locks. Each 64KB block (except the top and bottom blocks, total of 30 blocks) and each 4KB sector within the top/bottom blocks (total of 32 sectors) are equipped with an Individual Block Lock bit. When the lock bit is 0, the corresponding sector or block can be erased or programmed; when the lock bit is set to 1, Erase or Program commands issued to the corresponding sector or block will be ignored. When the device is powered on, all Individual Block Lock bits will be 1, so the entire memory array is protected from Erase/Program. An "Individual Block Unlock (39h)" instruction must be issued to unlock any specific sector or block.

The WPS bit in Status Register-3 is used to decide which Write Protect scheme should be used. When WPS=0 (factory default), the device will only utilize CMP, SEC, TB, BP[2:0] bits to protect specific areas of the array; when WPS=1, the device will utilize the Individual Block Locks for write protection.



## 7. STATUS AND CONFIGURATION REGISTERS

Three Status and Configuration Registers are provided for W25Q16JV. The Read Status Register-1/2/3 instructions can be used to provide status on the availability of the flash memory array, whether the device is write enabled or disabled, the state of write protection, Quad SPI setting, Security Register lock status, Erase/Program Suspend status, and output driver strength. The Write Status Register instruction can be used to configure the device write protection features, Quad SPI setting, Security Register OTP locks, and output driver strength. Write access to the Status Register is controlled by the state of the non-volatile Status Register Protect bits (SRL), the Write Enable instruction, and during Standard/Dual SPI operations.

### 7.1 Status Registers

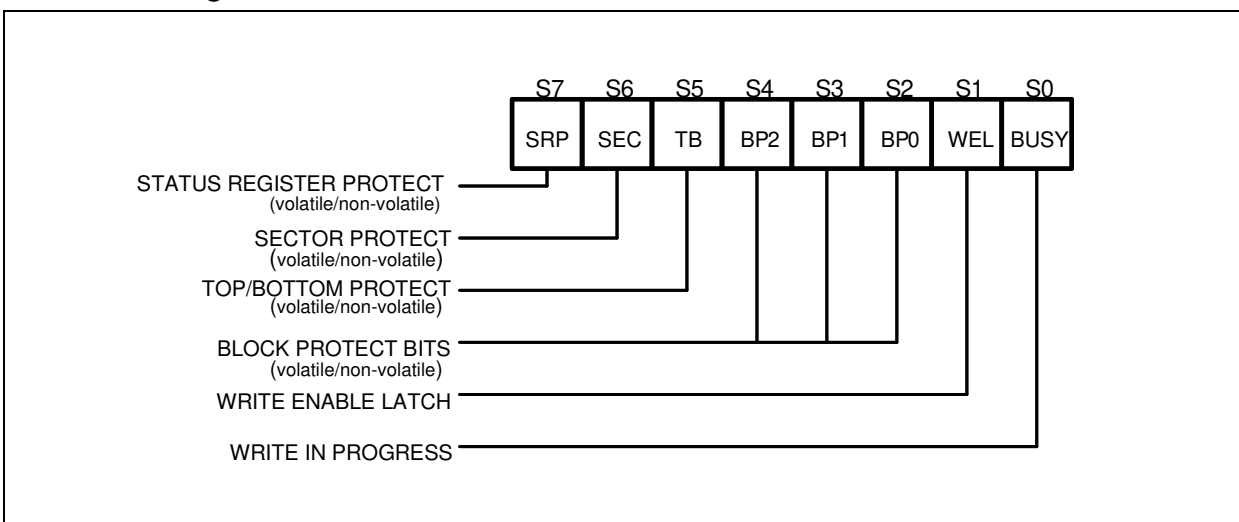


Figure 4a. Status Register-1

#### 7.1.1 Erase/Write In Progress (BUSY) – Status Only

BUSY is a read only bit in the status register (S0) that is set to a 1 state when the device is executing a Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase, Write Status Register or Erase/Program Security Register instruction. During this time the device will ignore further instructions except for the Read Status Register and Erase/Program Suspend instruction (see *tw*, *tPP*, *tSE*, *tBE*, and *tCE* in AC Characteristics). When the program, erase or write status/security register instruction has completed, the BUSY bit will be cleared to a 0 state indicating the device is ready for further instructions.

#### 7.1.2 Write Enable Latch (WEL) – Status Only

Write Enable Latch (WEL) is a read only bit in the status register (S1) that is set to 1 after executing a Write Enable Instruction. The WEL status bit is cleared to 0 when the device is write disabled. A write disable state occurs upon power-up or after any of the following instructions: Write Disable, Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase, Write Status Register, Erase Security Register and Program Security Register.

#### 7.1.3 Block Protect Bits (BP2, BP1, BP0) – Volatile/Non-Volatile Writable

The Block Protect Bits (BP2, BP1, BP0) are non-volatile read/write bits in the status register (S4, S3, and S2) that provide Write Protection control and status. Block Protect bits can be set using the Write Status Register Instruction (see *tw* in AC characteristics). All, none or a portion of the memory array can be protected from Program and Erase instructions (see Status Register Memory Protection table). The factory default setting for the Block Protection Bits is 0, none of the array protected.



#### **7.1.4 Top/Bottom Block Protect (TB) – Volatile/Non-Volatile Writable**

The non-volatile Top/Bottom bit (TB) controls if the Block Protect Bits (BP2, BP1, BP0) protect from the Top (TB=0) or the Bottom (TB=1) of the array as shown in the Status Register Memory Protection table. The factory default setting is TB=0. The TB bit can be set with the Write Status Register Instruction depending on the state of the SRL and WEL bits.

#### **7.1.5 Sector/Block Protect Bit (SEC) – Volatile/Non-Volatile Writable**

The non-volatile Sector/Block Protect bit (SEC) controls if the Block Protect Bits (BP2, BP1, BP0) protect either 4KB Sectors (SEC=1) or 64KB Blocks (SEC=0) in the Top (TB=0) or the Bottom (TB=1) of the array as shown in the Status Register Memory Protection table. The default setting is SEC=0.

#### **7.1.6 Complement Protect (CMP) – Volatile/Non-Volatile Writable**

The Complement Protect bit (CMP) is a non-volatile read/write bit in the status register (S14). It is used in conjunction with SEC, TB, BP2, BP1 and BP0 bits to provide more flexibility for the array protection. Once CMP is set to 1, previous array protection set by SEC, TB, BP2, BP1 and BP0 will be reversed. For instance, when CMP=0, a top 64KB block can be protected while the rest of the array is not; when CMP=1, the top 64KB block will become unprotected while the rest of the array become read-only. Please refer to the Status Register Memory Protection table for details. The default setting is CMP=0.



### 7.1.1 Status Register Protect SRP, SRL) – Volatile/Non-Volatile Writable

Three Status and Configuration Registers are provided for W25Q16JV. The Read Status Register-1/2/3 instructions can be used to provide status on the availability of the flash memory array, whether the device is write enabled or disabled, the state of write protection, Quad SPI setting, Security Register lock status, Erase/Program Suspend status, and output driver strength, The Write Status Register instruction can be used to configure the device write protection features, Quad SPI setting, Security Register OTP locks, output driver. Write access to the Status Register is controlled by the state of the non-volatile Status Register Protect bits (SRP, SRL), the Write Enable instruction, and during Standard/Dual SPI operations, the /WP pin.

SRL	SRP	/WP	Status Register	Description
0	0	X	Software Protection	/WP pin has no control. The Status register can be written to after a Write Enable instruction, WEL=1. [Factory Default]
0	1	0	Hardware Protected	When /WP pin is low the Status Register locked and cannot be written to.
0	1	1	Hardware Unprotected	When /WP pin is high the Status register is unlocked and can be written to after a Write Enable instruction, WEL=1.
1	X	X	Power Supply Lock-Down	Status Register is protected and cannot be written to again until the next power-down, power-up cycle. <sup>(1)</sup>
1	X	X	One Time Program <sup>(2)</sup>	Status Register is permanently protected and cannot be written to. <b>(enabled by adding prefix command AAh, 55h)</b>

1. When SRL =1 , a power-down, power-up cycle will change SRL =0 state.
2. Please contact Winbond for details regarding the special instruction sequence.

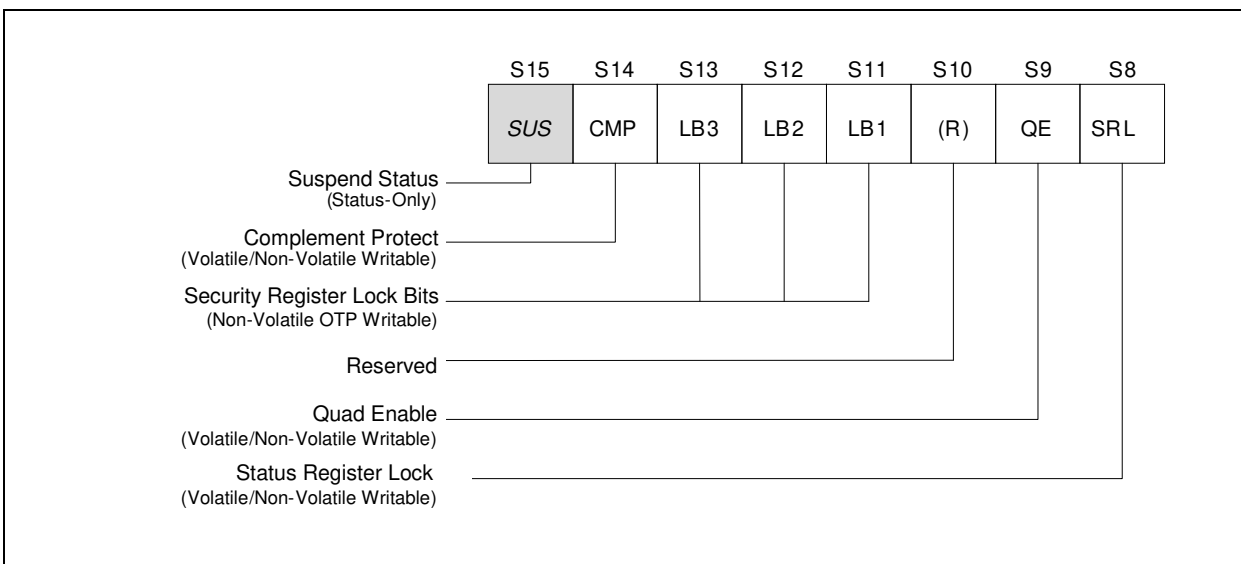


Figure 4b. Status Register-2

### 7.1.2 Erase/Program Suspend Status (SUS) – Status Only

The Suspend Status bit is a read only bit in the status register (S15) that is set to 1 after executing a Erase/Program Suspend (75h) instruction. The SUS status bit is cleared to 0 by Erase/Program Resume (7Ah) instruction as well as a power-down, power-up cycle.

### 7.1.3 Security Register Lock Bits (LB3, LB2, LB1) – Non-Volatile OTP Writable

The Security Register Lock Bits (LB3, LB2, LB1) are non-volatile One Time Program (OTP) bits in Status Register (S13, S12, S11) that provide the write protect control and status to the Security Registers. The default state of LB3-1 is 0, Security Registers are unlocked. LB3-1 can be set to 1 individually using the Write Status Register instruction. LB3-1 are One Time Programmable (OTP), once it's set to 1, the corresponding 256-Byte Security Register will become read-only permanently.

## 8. QUAD ENABLE (QE) – Volatile/Non-Volatile Writable

The Quad Enable (QE) bit is a non-volatile read/write bit in the status register (S9) that enables Quad SPI operation. When the QE bit is set to a 0 state (factory default for part numbers with ordering options "IM" & "JM"), the /HOLD are enabled, the device operates in Standard/Dual SPI modes. When the QE bit is set to a 1 (factory fixed default for part numbers with ordering options "IQ" & "JQ"), the Quad IO2 and IO3 pins are enabled, and /HOLD function is disabled, the device operates in Standard/Dual/Quad SPI modes.



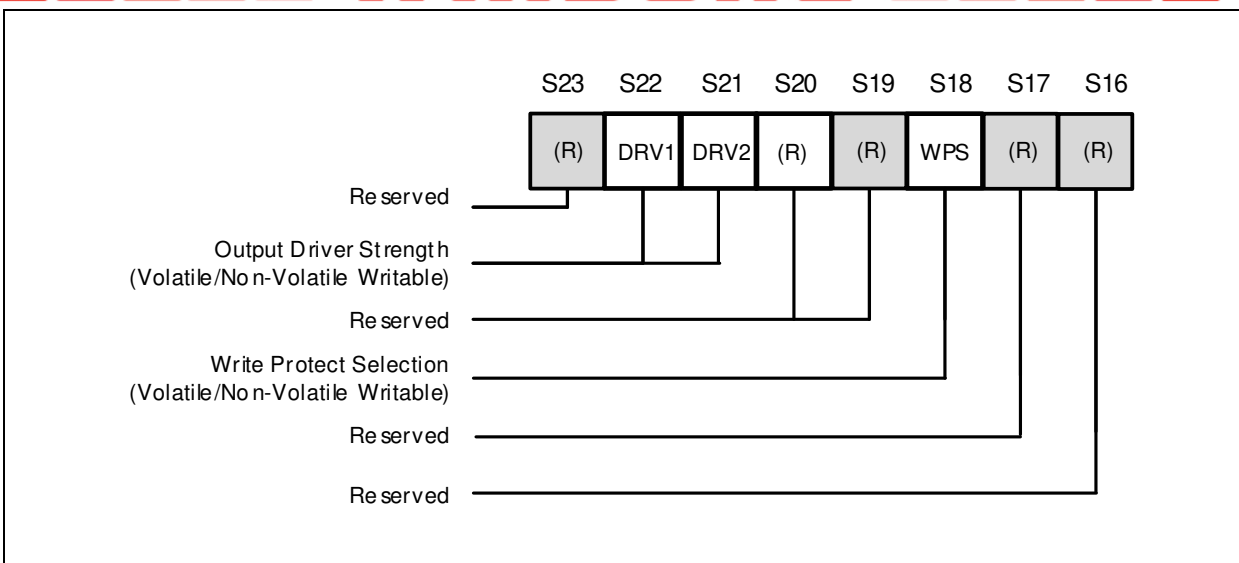


Figure 4c. Status Register-3

### 8.1.1 Write Protect Selection (WPS) – Volatile/Non-Volatile Writable

The WPS bit is used to select which Write Protect scheme should be used. When WPS=0, the device will use the combination of CMP, SEC, TB, BP[2:0] bits to protect a specific area of the memory array. When WPS=1, the device will utilize the Individual Block Locks to protect any individual sector or blocks. The default value for all Individual Block Lock bits is 1 upon device power on or after reset.

### 8.1.2 Output Driver Strength (DRV1, DRV0) – Volatile/Non-Volatile Writable

The DRV1 & DRV0 bits are used to determine the output driver strength for the Read operations.

DRV1, DRV0	Driver Strength
0, 0	100%
0, 1	75%
1, 0	50%
1, 1	25% (default)

### 8.1.3 Reserved Bits – Non Functional

There are a few reserved Status Register bits that may be read out as a “0” or “1”. It is recommended to ignore the values of those bits. During a “Write Status Register” instruction, the Reserved Bits can be written as “0”, but there will not be any effects.



## 8.1.4 W25Q16JV Status Register Memory Protection (WPS = 0, CMP = 0)

STATUS REGISTER <sup>(1)</sup>					W25Q16JV (16M-BIT) MEMORY PROTECTION <sup>(3)</sup>			
SEC	TB	BP2	BP1	BP0	PROTECTED BLOCK(S)	PROTECTED ADDRESSES	PROTECTED DENSITY	PROTECTED PORTION <sup>(2)</sup>
X	X	0	0	0	NONE	NONE	NONE	NONE
0	0	0	0	1	31	1F0000h – 1FFFFFFh	64KB	Upper 1/32
0	0	0	1	0	30 and 31	1E0000h – 1FFFFFFh	128KB	Upper 1/16
0	0	0	1	1	28 thru 31	1C0000h – 1FFFFFFh	256KB	Upper 1/8
0	0	1	0	0	24 thru 31	180000h – 1FFFFFFh	512KB	Upper 1/4
0	0	1	0	1	16 thru 31	100000h – 1FFFFFFh	1MB	Upper 1/2
0	1	0	0	1	0	000000h – 00FFFFh	64KB	Lower 1/32
0	1	0	1	0	0 and 1	000000h – 01FFFFh	128KB	Lower 1/16
0	1	0	1	1	0 thru 3	000000h – 03FFFFh	256KB	Lower 1/8
0	1	1	0	0	0 thru 7	000000h – 07FFFFh	512KB	Lower 1/4
0	1	1	0	1	0 thru 15	000000h – 0FFFFFFh	1MB	Lower 1/2
X	X	1	1	X	0 thru 31	000000h – 1FFFFFFh	2MB	ALL
1	0	0	0	1	31	1FF000h – 1FFFFFFh	4KB	U – 1/512
1	0	0	1	0	31	1FE000h – 1FFFFFFh	8KB	U – 1/256
1	0	0	1	1	31	1FC000h – 1FFFFFFh	16KB	U – 1/128
1	0	1	0	X	31	1F8000h – 1FFFFFFh	32KB	U – 1/64
1	1	0	0	1	0	000000h – 000FFFh	4KB	L – 1/512
1	1	0	1	0	0	000000h – 001FFFh	8KB	L – 1/256
1	1	0	1	1	0	000000h – 003FFFh	16KB	L – 1/128
1	1	1	0	X	0	000000h – 007FFFh	32KB	L – 1/64

**Notes:**

1. X = don't care
2. L = Lower; U = Upper
3. If any Erase or Program command specifies a memory region that contains protected data portion, this command will be ignored.



## 8.1.5 W25Q16JV Status Register Memory Protection (WPS = 0, CMP = 1)

STATUS REGISTER <sup>(1)</sup>					W25Q16JV (16M-BIT) MEMORY PROTECTION <sup>(3)</sup>			
SEC	TB	BP2	BP1	BP0	PROTECTED BLOCK(S)	PROTECTED ADDRESSES	PROTECTED DENSITY	PROTECTED PORTION <sup>(2)</sup>
X	X	0	0	0	0 thru 31	000000h – 1FFFFFFh	ALL	ALL
0	0	0	0	1	0 thru 30	000000h – 1EFFFFh	1,984KB	Lower 31/32
0	0	0	1	0	0 thru 29	000000h – 1DFFFFh	1,920KB	Lower 15/16
0	0	0	1	1	0 thru 27	000000h – 1BFFFFh	1,792KB	Lower 7/8
0	0	1	0	0	0 thru 23	000000h – 17FFFFh	1,536KB	Lower 3/4
0	0	1	0	1	0 thru 15	000000h – 0FFFFFFh	1MB	Lower 1/2
0	1	0	0	1	1 thru 31	010000h – 1FFFFFFh	1,984KB	Upper 31/32
0	1	0	1	0	2 and 31	020000h – 1FFFFFFh	1,920KB	Upper 15/16
0	1	0	1	1	4 thru 31	040000h – 1FFFFFFh	1,792KB	Upper 7/8
0	1	1	0	0	8 thru 31	080000h – 1FFFFFFh	1,536KB	Upper 3/4
0	1	1	0	1	16 thru 31	100000h – 1FFFFFFh	1MB	Upper 1/2
X	X	1	1	X	NONE	NONE	NONE	NONE
1	0	0	0	1	0 thru 31	000000h – 1FEFFFFh	2,044KB	L – 511/512
1	0	0	1	0	0 thru 31	000000h – 1FDFFFFh	2,040KB	L – 255/256
1	0	0	1	1	0 thru 31	000000h – 1FBFFFFh	2,032KB	L – 127/128
1	0	1	0	X	0 thru 31	000000h – 1F7FFFFh	2,016KB	L – 63/64
1	1	0	0	1	0 thru 31	001000h – 1FFFFFFh	2,044KB	U – 511/512
1	1	0	1	0	0 thru 31	002000h – 1FFFFFFh	2,040KB	U – 255/256
1	1	0	1	1	0 thru 31	004000h – 1FFFFFFh	2,032KB	U – 127/128
1	1	1	0	X	0 thru 31	008000h – 1FFFFFFh	2,016KB	U – 63/64

**Notes:**

1. X = don't care
2. L = Lower; U = Upper
3. If any Erase or Program command specifies a memory region that contains protected data portion, this command will be ignored.



8.1.6 W25Q16JV Individual Block Memory Protection (WPS=1)

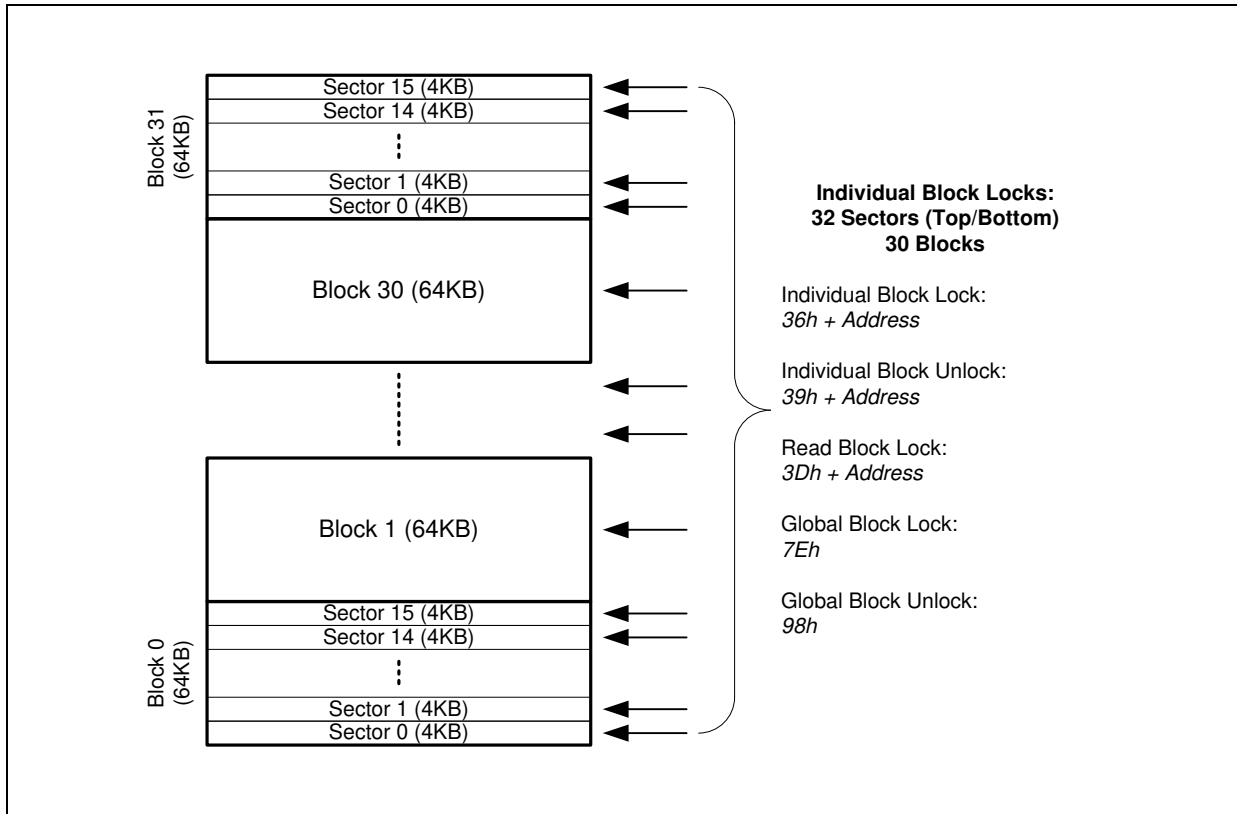


Figure 4d. Individual Block/Sector Locks

**Notes:**

1. Individual Block/Sector protection is only valid when WPS=1.
2. All individual block/sector lock bits are set to 1 by default after power up, all memory array is protected.



## 9. INSTRUCTIONS

The Standard/Dual/Quad SPI instruction set of the W25Q16JV consists of 48 basic instructions that are fully controlled through the SPI bus (see Instruction Set Table1-2). Instructions are initiated with the falling edge of Chip Select (/CS). The first byte of data clocked into the DI input provides the instruction code. Data on the DI input is sampled on the rising edge of clock with most significant bit (MSB) first.

Instructions vary in length from a single byte to several bytes and may be followed by address bytes, data bytes, dummy bytes (don't care), and in some cases, a combination. Instructions are completed with the rising edge of edge /CS. Clock relative timing diagrams for each instruction are included in Figures 5 through 57. All read instructions can be completed after any clocked bit. However, all instructions that Write, Program or Erase must complete on a byte boundary (/CS driven high after a full 8-bits have been clocked) otherwise the instruction will be ignored. This feature further protects the device from inadvertent writes. Additionally, while the memory is being programmed or erased, or when the Status Register is being written, all instructions except for Read Status Register will be ignored until the program or erase cycle has completed.

### 9.1 Device ID and Instruction Set Tables

#### 9.1.1 *Manufacturer and Device Identification*

<b>MANUFACTURER ID</b>	<b>(MF7 - MF0)</b>	
Winbond Serial Flash	EFh	
<b>Device ID</b>	<b>(ID7 - ID0)</b>	<b>(ID15 - ID0)</b>
<b>Instruction</b>	<b>ABh, 90h, 92h, 94h</b>	<b>9Fh</b>
W25Q16JV-IQ/JQ	14h	4015h
W25Q16JV-IM*/JM*	14h	7015h

Note: For DTR, QPI supporting, please refer to W25Q16JV DTR datasheet.

9.1.2 Instruction Set Table 1 (Standard SPI Instructions) <sup>(1)</sup>

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7
Number of Clock <sub>(1-1-1)</sub>	8	8	8	8	8	8	8
Write Enable	06h						
Volatile SR Write Enable	50h						
Write Disable	04h						
Release Power-down / ID	ABh	Dummy	Dummy	Dummy	(ID7-ID0) <sup>(2)</sup>		
Manufacturer/Device ID	90h	Dummy	Dummy	00h	(MF7-MF0)	(ID7-ID0)	
JEDEC ID	9Fh	(MF7-MF0)	(ID15-ID8)	(ID7-ID0)			
Read Unique ID	4Bh	Dummy	Dummy	Dummy	Dummy	(UID63-0)	
Read Data	03h	A23-A16	A15-A8	A7-A0	(D7-D0)		
Fast Read	0Bh	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)	
Page Program	02h	A23-A16	A15-A8	A7-A0	D7-D0	D7-D0 <sup>(3)</sup>	
Sector Erase (4KB)	20h	A23-A16	A15-A8	A7-A0			
Block Erase (32KB)	52h	A23-A16	A15-A8	A7-A0			
Block Erase (64KB)	D8h	A23-A16	A15-A8	A7-A0			
Chip Erase	C7h/60h						
Read Status Register-1	05h	(S7-S0) <sup>(2)</sup>					
Write Status Register-1 <sup>(4)</sup>	01h	(S7-S0) <sup>(4)</sup>					
Read Status Register-2	35h	(S15-S8) <sup>(2)</sup>					
Write Status Register-2	31h	(S15-S8)					
Read Status Register-3	15h	(S23-S16) <sup>(2)</sup>					
Write Status Register-3	11h	(S23-S16)					
Read SFDP Register	5Ah	00	00	A7-A0	Dummy	(D7-D0)	
Erase Security Register <sup>(5)</sup>	44h	A23-A16	A15-A8	A7-A0			
Program Security Register <sup>(5)</sup>	42h	A23-A16	A15-A8	A7-A0	D7-D0 <sup>(3)</sup>		
Read Security Register <sup>(5)</sup>	48h	A23-A16	A15-A8	A7-A0	Dummy	(D7-D0)	
Global Block Lock	7Eh						
Global Block Unlock	98h						
Read Block Lock	3Dh	A23-A16	A15-A8	A7-A0	(L7-L0)		
Individual Block Lock	36h	A23-A16	A15-A8	A7-A0			
Individual Block Unlock	39h	A23-A16	A15-A8	A7-A0			
Erase / Program Suspend	75h						
Erase / Program Resume	7Ah						
Power-down	B9h						
Enable Reset	66h						
Reset Device	99h						

9.1.3 Instruction Set Table 2 (Dual/Quad SPI Instructions)<sup>(1)</sup>

Data Input Output	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7	Byte 8	Byte 9
Number of Clock <sup>(1-1-2)</sup>	8	8	8	8	4	4	4	4	4
Fast Read Dual Output	3Bh	A23-A16	A15-A8	A7-A0	Dummy	Dummy	(D7-D0) <sup>(7)</sup>		
Number of Clock <sup>(1-2-2)</sup>	8	4	4	4	4	4	4	4	4
Fast Read Dual I/O	BBh	A23-A16 <sup>(6)</sup>	A15-A8 <sup>(6)</sup>	A7-A0 <sup>(6)</sup>	Dummy <sup>(11)</sup>	(D7-D0) <sup>(7)</sup>			
Mftr./Device ID Dual I/O	92h	A23-A16 <sup>(6)</sup>	A15-A8 <sup>(6)</sup>	00 <sup>(6)</sup>	Dummy <sup>(11)</sup>	(MF7-MF0)	(ID7-ID0) <sup>(7)</sup>		
Number of Clock <sup>(1-1-4)</sup>	8	8	8	8	2	2	2	2	2
Quad Input Page Program	32h	A23-A16	A15-A8	A7-A0	(D7-D0) <sup>(9)</sup>	(D7-D0) <sup>(3)</sup>	...		
Fast Read Quad Output	6Bh	A23-A16	A15-A8	A7-A0	Dummy	Dummy	Dummy	Dummy	(D7-D0) <sup>(10)</sup>
Number of Clock <sup>(1-4-4)</sup>	8	2 <sup>(8)</sup>	2 <sup>(8)</sup>	2 <sup>(8)</sup>	2	2	2	2	2
Mftr./Device ID Quad I/O	94h	A23-A16	A15-A8	00	Dummy <sup>(11)</sup>	Dummy	Dummy	(MF7-MF0)	(ID7-ID0)
Fast Read Quad I/O	EBh	A23-A16	A15-A8	A7-A0	Dummy <sup>(11)</sup>	Dummy	Dummy	(D7-D0)	
Set Burst with Wrap	77h	Dummy	Dummy	Dummy	W8-W0				

**Notes:**

- Data bytes are shifted with Most Significant Bit first. Byte fields with data in parenthesis “( )” indicate data output from the device on either 1, 2 or 4 IO pins.
- The Status Register contents and Device ID will repeat continuously until /CS terminates the instruction.
- At least one byte of data input is required for Page Program, Quad Page Program and Program Security Registers, up to 256 bytes of data input. If more than 256 bytes of data are sent to the device, the addressing will wrap to the beginning of the page and overwrite previously sent data.
- Write Status Register-1 (01h) can also be used to program Status Register-1&2, see section 8.2.5.
- Security Register Address:  
 Security Register 1: A23-16 = 00h; A15-8 = 10h; A7-0 = byte address  
 Security Register 2: A23-16 = 00h; A15-8 = 20h; A7-0 = byte address  
 Security Register 3: A23-16 = 00h; A15-8 = 30h; A7-0 = byte address
- Dual SPI address input format:  
 IO0 = A22, A20, A18, A16, A14, A12, A10, A8 A6, A4, A2, A0, M6, M4, M2, M0  
 IO1 = A23, A21, A19, A17, A15, A13, A11, A9 A7, A5, A3, A1, M7, M5, M3, M1
- Dual SPI data output format:  
 IO0 = (D6, D4, D2, D0)  
 IO1 = (D7, D5, D3, D1)
- Quad SPI address input format:  
 IO0 = A20, A16, A12, A8, A4, A0, M4, M0  
 IO1 = A21, A17, A13, A9, A5, A1, M5, M1  
 IO2 = A22, A18, A14, A10, A6, A2, M6, M2  
 IO3 = A23, A19, A15, A11, A7, A3, M7, M3
- Set Burst with Wrap input format:  
 IO0 = x, x, x, x, x, x, W4, x  
 IO1 = x, x, x, x, x, x, W5, x  
 IO2 = x, x, x, x, x, x, W6, x  
 IO3 = x, x, x, x, x, x, x, x
- Quad SPI data input/output format:  
 IO0 = (D4, D0, .....)  
 IO1 = (D5, D1, .....)  
 IO2 = (D6, D2, .....)  
 IO3 = (D7, D3, .....)
- Fast Read Quad I/O data output format:  
 IO0 = (x, x, x, x, D4, D0, D4, D0)  
 IO1 = (x, x, x, x, D5, D1, D5, D1)  
 IO2 = (x, x, x, x, D6, D2, D6, D2)  
 IO3 = (x, x, x, x, D7, D3, D7, D3)
- The first dummy is M7-M0 should be set to Fxh



## 9.2 Instruction Descriptions

### 9.2.1 Write Enable (06h)

The Write Enable instruction (Figure 5) sets the Write Enable Latch (WEL) bit in the Status Register to a 1. The WEL bit must be set prior to every Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase, Write Status Register and Erase/Program Security Registers instruction. The Write Enable instruction is entered by driving /CS low, shifting the instruction code “06h” into the Data Input (DI) pin on the rising edge of CLK, and then driving /CS high.

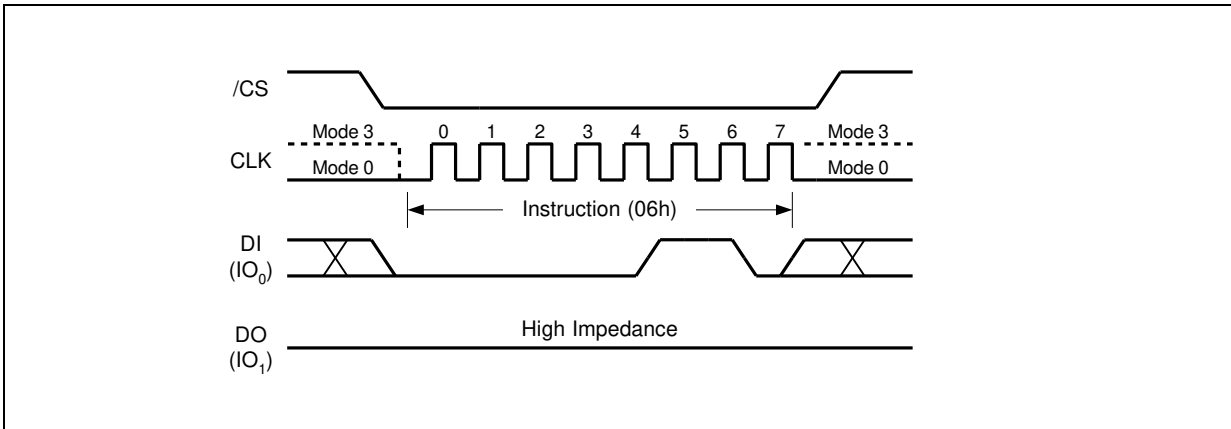


Figure 5. Write Enable Instruction

### 9.2.2 Write Enable for Volatile Status Register (50h)

The non-volatile Status Register bits described in section 7.1 can also be written to as volatile bits. This gives more flexibility to change the system configuration and memory protection schemes quickly without waiting for the typical non-volatile bit write cycles or affecting the endurance of the Status Register non-volatile bits. To write the volatile values into the Status Register bits, the Write Enable for Volatile Status Register (50h) instruction must be issued prior to a Write Status Register (01h) instruction. Write Enable for Volatile Status Register instruction (Figure 6) will not set the Write Enable Latch (WEL) bit, it is only valid for the Write Status Register instruction to change the volatile Status Register bit values.

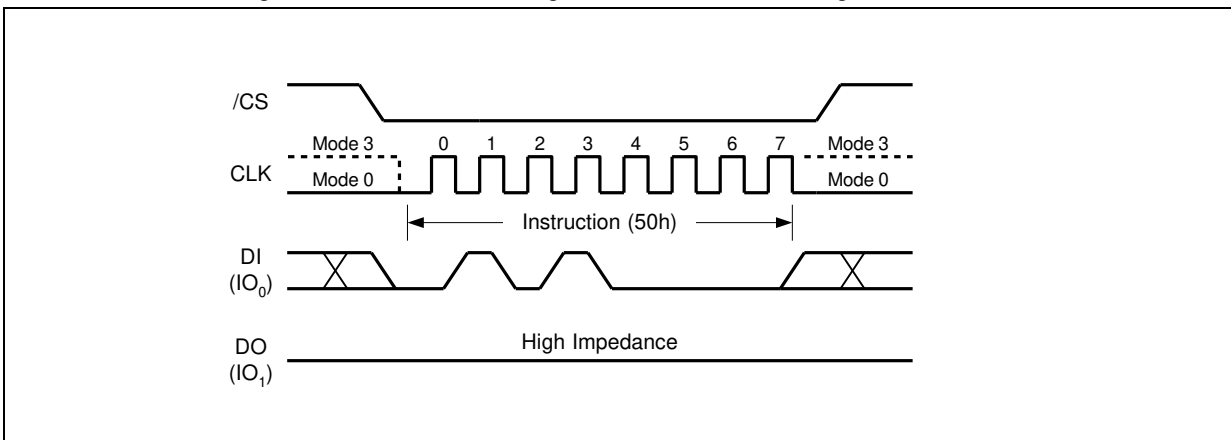


Figure 6. Write Enable for Volatile Status Register Instruction





9.2.3 Write Disable (04h)

The Write Disable instruction (Figure 7) resets the Write Enable Latch (WEL) bit in the Status Register to a 0. The Write Disable instruction is entered by driving /CS low, shifting the instruction code “04h” into the DI pin and then driving /CS high. Note that the WEL bit is automatically reset after Power-up and upon completion of the Write Status Register, Erase/Program Security Registers, Page Program, Quad Page Program, Sector Erase, Block Erase, Chip Erase and Reset instructions.

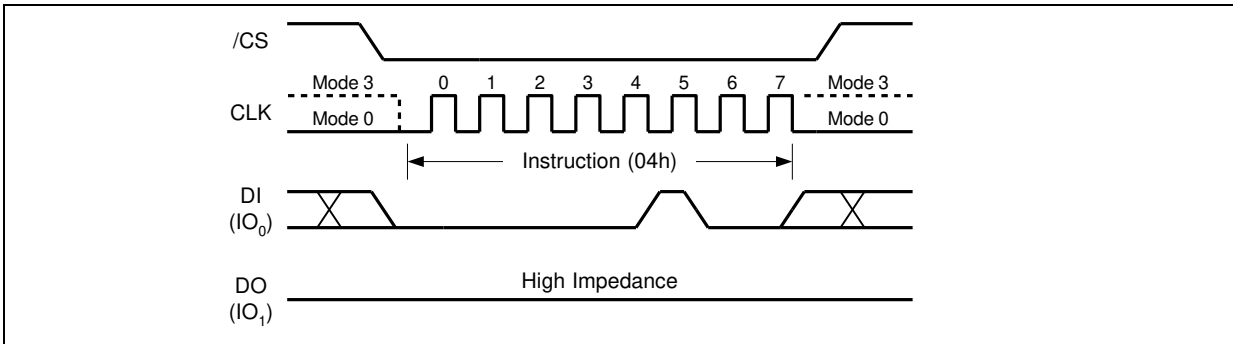


Figure 7. Write Disable Instruction

9.2.4 Read Status Register-1 (05h), Status Register-2 (35h) & Status Register-3 (15h)

The Read Status Register instructions allow the 8-bit Status Registers to be read. The instruction is entered by driving /CS low and shifting the instruction code “05h” for Status Register-1, “35h” for Status Register-2 or “15h” for Status Register-3 into the DI pin on the rising edge of CLK. The status register bits are then shifted out on the DO pin at the falling edge of CLK with most significant bit (MSB) first as shown in Figure 8. Refer to section 7.1 for Status Register descriptions.

The Read Status Register instruction may be used at any time, even while a Program, Erase or Write Status Register cycle is in progress. This allows the BUSY status bit to be checked to determine when the cycle is complete and if the device can accept another instruction. The Status Register can be read continuously, as shown in Figure 8. The instruction is completed by driving /CS high.

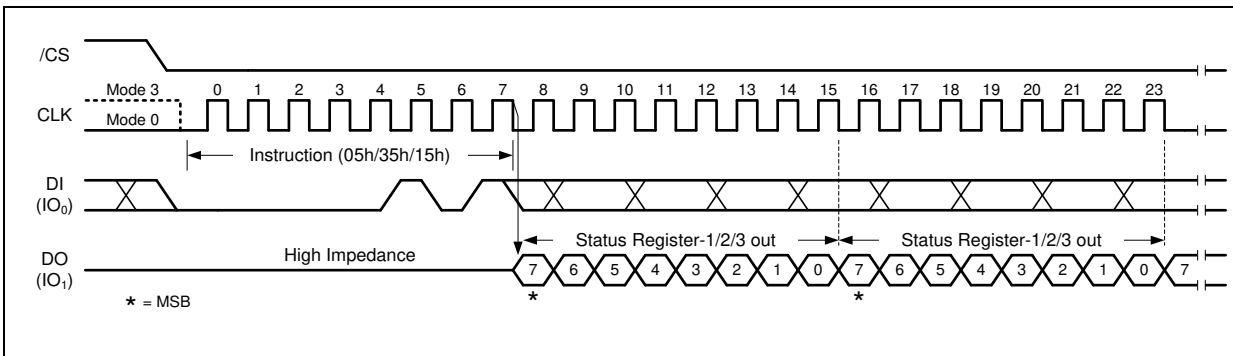


Figure 8. Read Status Register Instruction



### 9.2.5 Write Status Register-1 (01h), Status Register-2 (31h) & Status Register-3 (11h)

The Write Status Register instruction allows the Status Registers to be written. The writable Status Register bits include: SEC, TB, BP[2:0] in Status Register-1; CMP, LB[3:1], QE, SRL in Status Register-2; DRV1, DRV0, WPS in Status Register-3. All other Status Register bit locations are read-only and will not be affected by the Write Status Register instruction. LB[3:1] are non-volatile OTP bits, once it is set to 1, it cannot be cleared to 0.

To write non-volatile Status Register bits, a standard Write Enable (06h) instruction must previously have been executed for the device to accept the Write Status Register instruction (Status Register bit WEL must equal 1). Once write enabled, the instruction is entered by driving /CS low, sending the instruction code "01h/31h/11h", and then writing the status register data byte as illustrated in Figure 9a.

To write volatile Status Register bits, a Write Enable for Volatile Status Register (50h) instruction must have been executed prior to the Write Status Register instruction (Status Register bit WEL remains 0). However, SRL and LB[3:1] cannot be changed from "1" to "0" because of the OTP protection for these bits. Upon power off or the execution of a Software/Hardware Reset, the volatile Status Register bit values will be lost, and the non-volatile Status Register bit values will be restored.

During non-volatile Status Register write operation (06h combined with 01h/31h/11h), after /CS is driven high, the self-timed Write Status Register cycle will commence for a time duration of  $t_w$  (See AC Characteristics). While the Write Status Register cycle is in progress, the Read Status Register instruction may still be accessed to check the status of the BUSY bit. The BUSY bit is a 1 during the Write Status Register cycle and a 0 when the cycle is finished and ready to accept other instructions again. After the Write Status Register cycle has finished, the Write Enable Latch (WEL) bit in the Status Register will be cleared to 0.

During volatile Status Register write operation (50h combined with 01h/31h/11h), after /CS is driven high, the Status Register bits will be refreshed to the new values within the time period of  $t_{SHSL2}$  (See AC Characteristics). BUSY bit will remain 0 during the Status Register bit refresh period.

Refer to section 7.1 for Status Register descriptions.

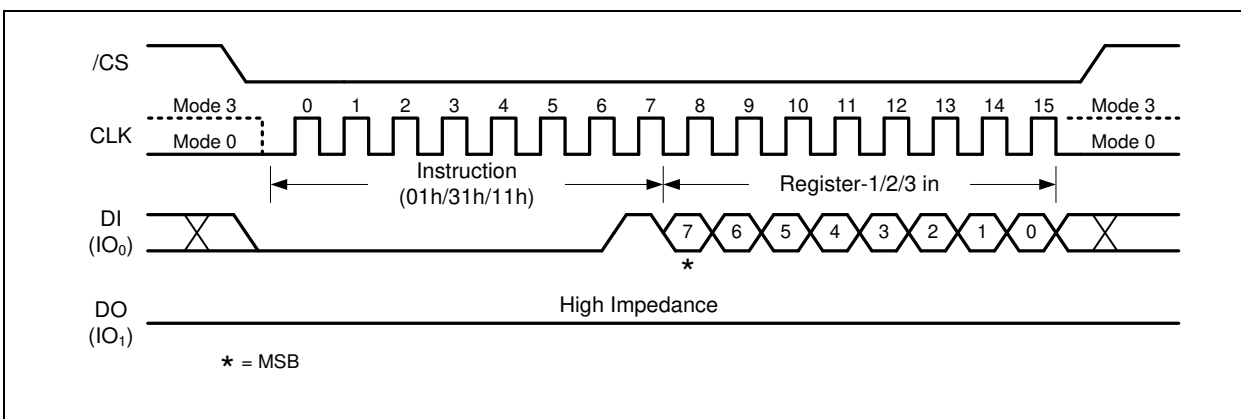


Figure 9a. Write Status Register-1/2/3 Instruction